

02-10-1999

ATTY. DOCKET NO: AB-747 US

U.S. DEPARTMENT OF COMMERCE

SHEET

Patent and Trademark Office



To the Honorable Commissioner

100963162

ie attached original documents or copy thereof.

## 1. Name of conveying party:

(a) Sung Jin Kim

(b)

(c)

Additional name(s) of conveying party(ies) attached?

1-29-99

☐ Yes ☒ No

## 2. Name and address of receiving parties:

Name: ANAM Semiconductor Inc.

Internal Address: \_\_\_\_\_

Street Address: 280-8 Sungsu 2-Ga Sungdong-Ku

City Seoul Country Korea ZIP 133-120Additional name(s) & address(es) attached? ☒ Yes ☐ No

## 3. Nature of Conveyance:

☒ Assignment ☐ Merger☐ Security Agreement ☐ Change of Name☐ Other \_\_\_\_\_Execution Date: January 15, 1999

## 4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: January 15, 1999

## A. Patent Application No.(s) -

Title: Method of Molding Ball Grid Array Semiconductor Packages

## B. Patent No.(s)

09/240423

Additional numbers attached? ☐ Yes ☒ No

## 5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Don C. LawrenceInternal Address: SKJERVEN, MORRILL, MacPHERSON,FRANKLIN & FRIEL LLPStreet Address: 25 METRO DRIVE, SUITE 700City SAN JOSE State CA ZIP 951106. Total number of applications and patents involved: 1

## 7. Total fee (37 CFR 3.41): .....\$40.00

- ☒ Authorized to be charged to Deposit Account 19-2386
- ☒ Charge Deposit Account 19-2386 for any additional fees required for this conveyance and credit deposit account 19-2386 any amounts overpaid

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## 8. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Don C. Lawrence Reg. No. 31,975  
Name of Person SigningDon C. Lawrence  
Signature1/29/99  
Date

Total number of pages comprising cover sheet: 3

PATENT  
REEL: 9743 FRAME: 0073

**PATENTS ONLY**

the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

Additional name(s) of conveying party(ies):

2. Additional Names and address of receiving party:

Name: AMKOR Technology, Inc.

Internal Address: \_\_\_\_\_

Street Address: 1900 S. Price Road

City Chandler State Arizona ZIP 85248-1604

Name: \_\_\_\_\_

Internal Address: \_\_\_\_\_

Street Address: \_\_\_\_\_

City \_\_\_\_\_ State \_\_\_\_\_ ZIP \_\_\_\_\_

Name: \_\_\_\_\_

Internal Address: \_\_\_\_\_

Street Address: \_\_\_\_\_

City \_\_\_\_\_ State \_\_\_\_\_ ZIP \_\_\_\_\_

Additional name(s) & address(es) attached? ☐ Yes ☒ No

Additional Application number(s) or patent number(s):

A. Patent Application No.(s)

B. Patent No.(s)

**ASSIGNMENT**

For good and valuable consideration, receipt of which is hereby acknowledged, I

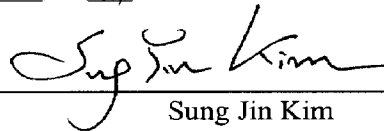
Sung Jin Kim                                      of                      602-1302, Chang-Mi APT, Hagae 3- Dong  
Nowan-Ku, Seoul, Korea

hereby sell, assign and transfer to ANAM Semiconductor Inc., a Korean corporation, having a place of business at 280-8 Sungsu 2-Ga Sungdong-Ku, Seoul 133-120, Korea, its successors and assigns, and AMKOR Technology, Inc., a Delaware corporation, having a place of business at 1900 S. Price Road, Chandler, AZ 85248-1604, U.S.A., its successors and assigns, the entire right, title and interest throughout the world in my invention in

Method of Molding Ball Grid Array Semiconductor Packages

for which I have executed a United States patent application on or about the date of this assignment, and all patent applications and patents of every country for said invention, including divisions, reissues, continuations and extensions thereof, and all rights of priority resulting from the filing of said applications; I authorize the above-named assignee to apply for patents of foreign countries for said invention, and to claim all rights of priority without further authorization from me; I agree to execute all papers useful in connection with said United States and foreign applications, and generally to do everything possible to aid said assignee, their successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in all countries; and I request the Commissioner of Patents and Trademarks to issue all patents granted for said invention to the above-named assignee, its successors and assigns.

Executed this 15th day of January, 19 99.

  
Sung Jin Kim

WITNESSED:

Tea Rok Jung  
Signature

1/15/99  
Date

Jan. 15, 1999  
Type or print name of witness